

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

1. (currently amended) A method of manufacturing a circuit board, comprising ~~the steps of:~~

vacuum-adhering a metal layer on a surface of a core substrate;

forming a multilayered body, in which cable patterns on different layers insulated by an insulating layer are electrically connected, on ~~the metal layer adhered to the core substrate by a buildup process~~; and

separating said multilayered body from said core substrate together with said metal layer by breaking the vacuum state between said core substrate and said metal layer,

~~wherein a metal layer is vacuum-adhered on said core substrate,~~

~~said multilayered body is formed on said metal layer by the buildup process, and~~

~~said multilayered body is separated from said core substrate together with said metal layer by breaking the vacuum state between said core substrate and said metal layer.~~

2. (original) A method of manufacturing a circuit board, comprising:

forming a multilayered body, in which cable patterns on different layers insulated by an insulating layer are electrically connected, on a core substrate by a buildup process; and

separating said multilayered body from said core substrate,

wherein a first metal layer is adhered on said core substrate,

a second metal layer is vacuum-adhered on said first metal layer,

said multilayered body is formed on said second metal layer by the buildup process, and

said multilayered body is separated from said core substrate together with said second metal layer by breaking the vacuum state between said first metal layer and said second metal layer.

3. (original) The method according to claim 2,

wherein said second metal layer is broader than said first metal layer,

an outer edge of said second metal layer, which is vacuum-adhered on said first metal layer, is adhered on said core substrate, and

 said multilayered body and said core substrate are cut at a position slightly shifted inward from an outer edge of said first metal layer so as to break the vacuum state between said first metal layer and said second metal layer, whereby said multilayered body is separated from said core substrate together with said second metal layer.

4. (currently amended) ~~A method of manufacturing a circuit board,~~

~~comprising the steps of:~~

~~forming a multilayered body, in which cable patterns on different layers insulated by an insulating layer are electrically connected, on a core substrate by a buildup process;~~

~~separating said multilayered body from said core substrate; and~~

~~applying a prescribed treatment to said multilayered body which has been separated~~The method according to claim 1, wherein said multilayered body is formed by a buildup process.

5. (new) A method of manufacturing a circuit board, comprising:

adhering a first metal layer on a surface of a core substrate by an adhesive layer;

vacuum-adhering a second metal layer on said first metal layer;

forming a multilayered body, in which cable patterns on different layers insulated by an insulating layer are electrically connected, on the second metal layer; and

separating said multilayered body from said first metal layer together with said second metal layer by breaking the vacuum state between said first metal layer and said second metal layer.

6. (new) A method of manufacturing a circuit board, comprising:

vacuum-adhering a second metal layer on a first metal layer, which is smaller than said second metal layer;

adhering an outer edge of said second metal layer on said core substrate by said adhesive layer, which is provided on the surface of said core substrate;

forming a multilayered body, in which cable patterns on different layers insulated by an insulating layer are electrically connected, on said second metal layer; and

cutting said multilayered body at a position slightly shifted inward from an outer edge of said first metal layer, whereby said multilayered body is separated from said core substrate together with said second metal layer.

7. (new) The method according to claim 5, wherein said multilayered body is formed by a buildup process.

8. (new) The method according to claim 6, wherein said multilayered body is formed by a buildup process.

9. (new) The method according to claim 1, wherein a third metal layer is formed on a surface of an insulating layer of said multilayered body, which is formed on the opposite of said second metal layer, before separating said multilayered body.

10. (new) The method according to claim 5, wherein a third metal layer is formed on a surface of an insulating layer of said multilayered body, which is formed on the opposite of said second metal layer, before separating said multilayered body.

11. (new) The method according to claim 6, wherein a third metal layer is formed on a surface of an insulating layer of said multilayered body, which is formed on the opposite of said second metal layer, before separating said multilayered body.

12. (new) The method according to claim 5, wherein an outer metal layer is further formed on said second metal layer, and said outer metal layer is made of a metal which is not corroded by an etching solution for removing said second metal layer only.

13. (new) The method according to claim 6, wherein an outer metal layer is further formed on said second metal layer, and said outer metal layer is made of a metal which is not corroded by an etching solution for removing said second metal layer only.

14. (new) The method according to claim 13, wherein said metal layer is removed by etching so as to form bumps on the cable patterns.

15. (new) The method according to claim 14, wherein said metal layer is removed by etching so as to form bumps on the cable patterns.